

# MOCAS

INTERNATIONAL CONFERENCE ON  
MODERN CIRCUITS AND SYSTEMS TECHNOLOGIES

- 11-13 June 2025
- Dresden University of Technology (TUD), Dresden, Germany
- <https://tud.de/ing/mocast2025>

## Special Session Announcement: EMERGING MEMORY DEVICES FOR IN-MEMORY AI: FROM MATERIALS TO SYSTEM INTEGRATION



The 14th International Conference on Modern Circuits and Systems Technologies (MOCAS) aims to bring together leading academic and industrial scientists and researchers to exchange and share their knowledge and experiences about all aspects of Circuits and Systems.

### Session Description:

Scaling AI requires rethinking computing architectures beyond von Neumann constraints. **Emerging memory devices** enable **in-memory computing (IMC)**, reducing power and latency by performing computation within the memory itself.

At the **device level**, advances in **materials, switching mechanisms, and fabrication techniques** allow for highly dense, low-power computation. At the **circuit level**, crossbar arrays and mixed-signal processing enable efficient **matrix-vector multiplications (MVM)** for AI acceleration. At the **system level**, hardware-software co-design optimizes precision, reliability, and real-world deployment.

This session will explore how **device physics, circuit design, and AI architectures** come together to enable the next generation of **memory-centric AI computing**.

### Special Session Organizers:

**Alptekin Vardar**, Fraunhofer IPMS, Germany  
**Maximilian Lederer**, Fraunhofer IPMS, Germany  
**Thomas Kämpfe**, Fraunhofer IPMS, Germany

### Important Dates:

**17.03.2025**  
Deadline for  
Regular Paper  
Submission

**17.03.2025**  
**Deadline for  
Special Session  
Paper  
Submission**

**17.04.2025**  
Acceptance  
Notification  
for Papers

**24.04.2025**  
Camera-ready  
Submission  
for all  
Papers

**24.04.2025**  
Early Bird  
Registration  
deadline

**11.-13.06.2025**  
MOCAS 2025  
conference in  
Dresden

### List of Topics (but not limited to):

- **Device-Level Innovations for In-Memory Computing**  
Advances in memristive, ferroelectric, and magnetic devices for AI, focusing on switching mechanisms, material challenges, and strategies to improve variability, endurance, and reliability.
- **In-Memory Computing Architectures and Circuits**  
Crossbar-based accelerators for matrix-vector multiplication, mixed-signal and analog computing for deep learning, and circuit designs optimized for low-power AI workloads.
- **Hardware-Software Co-Design**  
Precision-aware AI models, hardware-aware training, and compiler frameworks to co-optimize performance, power, and accuracy in memory-centric systems.
- **Use Cases and Applications**  
Energy-efficient machine learning inference, secure and private AI execution on-chip to reduce attack surfaces, and ultra-low-power AI solutions for real-time processing in edge devices.
- **Security, Reliability, and Future Directions**  
Error correction and noise compensation for stable operations, resilient architectures for fault tolerance, and emerging trends in AI models optimized for in-memory computing and hybrid memory systems.

MOCAS is Technically Sponsored by IEEE. All accepted papers are expected to be included in IEEE Xplore and will be indexed by EI.

Authors of selected accepted papers will be invited to submit extended version of their paper to the MOCAS Special Issue at **Advanced Electronic Materials**.

